

FILM ADHESIVE FOR SEALING, FILM LAMINATE FOR SEALING AND
SEALING METHOD

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ABSTRACT

10 A film adhesive for sealing a plurality of chip-type devices on
a substrate at one time, including an adhesive layer of an
adhesive composition which exhibits a minimum value of a
storage modulus of elasticity before curing from 1×10^3 to $5 \times$
15 10^5 Pa measured by using a dynamic visco-elasticity measuring
apparatus while elevating the temperature from 80°C to 150°C at
an elevating temperature rate of $2.4^\circ\text{C}/\text{min}$ and at a shearing
rate of $6.28 \text{ rad}/\text{sec}$ and a storage modulus of elasticity after
curing from 5×10^5 to 5×10^7 Pa measured by using a dynamic
visco-elasticity measuring apparatus at a sample temperature of
 150°C in a tensile mode at a measuring frequency of 6.28
rad/sec.